SEMICONDUCTOR ASSEMBLY WITH IMPROVED DIE ATTACHMENT TO A CARRIER

Abstract of the Disclosure

A semiconductor assembly (100), formed with a carrier (102) mounted with a die (104), has an electrically conductive planar surface for electrically coupling to an electrically conductive pattern (106) on the carrier (102). The pattern (106) has a plurality of electrically interconnected members (204) exposing segments (112) of a non-conductive substrate (108) of the carrier (102). Surrounding the pattern (106) is a border (110) raised above, or recessed into, the non-conductive substrate (108). One or more conductive pads (208) outside the border (110) are associated with the pattern (106). An adhesive is used to attach the die (104) to the carrier (102) and is electrically conductive or non-conductive. The border (110) prevents a resin, applied over the die (104) upon attachment, from flowing out to other areas of the carrier (102).

FIG. 1 accompanies this abstract.